



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	William Hong, et al.	§	Examiner:	Thanh T. Nguyen
Serial No.:	10/714,985	§	Art Unit:	2813
Filed:	November 17, 2003	§	Conf. No.:	2268
For:	Copper CMP Defect Reduction by Extra Slurry Polish	§		

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office action of August 24, 2004, please amend the above-identified application as follows:

Amendments to the Title:

Please change the title to read, in its entirety:

--Chemical Mechanical Polishing Process with Reduced Defects in a Copper Process--

Amendments to the Specification are provided on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Remarks/Arguments begin on page 8 of this paper.

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